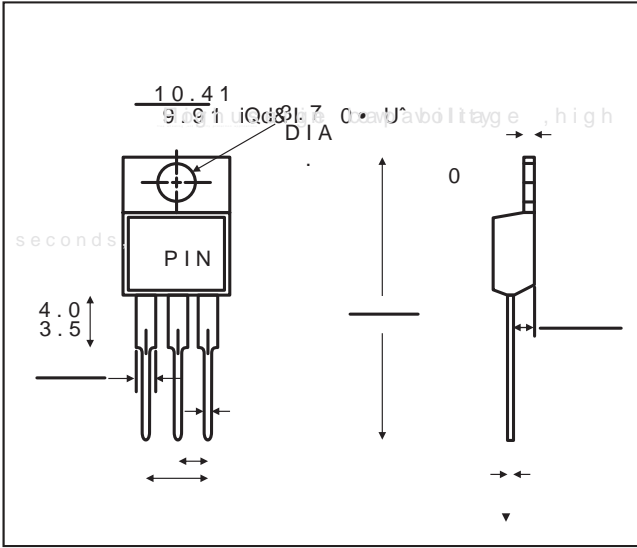


72 \$% 3/\$67, & & 25 (& 7,), (56

High temperature soldering guaranteed: 260 C/10 seconds
 0.25"(6.35mm) from case
 Component according to RoHS 2002/95/EC
 WEEE 2002/96/EC

0 (& + \$ 1, & \$ / ' \$ 7 \$

2. Reverse recovery test conditions



0 \$; , 080 5 \$ 7 , 1 * 6 \$ 1 ' & + \$ 5 \$ & 7 (5 , 6 7 , & 6

f & \$ P E L H G W S H U D X X O R H W K H U Z R L W H G

		Symbols	MURF 1620CT	MURF 1640CT	MURF 1660CT	Units
Maximum repetitive peak reverse voltage		V_{RRM}	200	400	600	Volts
Maximum RMS voltage		V_{RMS}	140	280	420	Volts
Maximum DC blocking voltage		V_{DC}	200	400	600	Volts
Maximum average forward rectified current (see Fig. 4)	Total device	I_{AV}	8.0			Amps
Peak forward surge current (8.3ms single sine-wave superimposed on rated load (JEDEC method))		I_{FSM}				Amps
Maximum instantaneous forward voltage at 10.0 A (Note 1)		V_F	0.975	1.3	1.7	Volts
Maximum instantaneous reverse current at rated DC blocking voltage (Note 1)	$T_s = 20^\circ C$	I_R	5			uA
	$T_s = 25^\circ C$		10			
Maximum Reverse Recovery Time (Note 2)			35			ns
Typical thermal resistance (Note 3) $R_{\theta JC}$			3.0			C/W
Operating junction temperature range		T_{JG}	-65 to +175			C
Storage temperature range		T_{STG}	-65 to +175			°C

$F = 0.5 A_r = 1.0 A, I_{rr} = 0.25 A$

3. Thermal resistance from junction to case

CHARACTE

